



Product/Process Change Notice - PCN 14_0259 Rev. A

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

PCN Title: Assembly Transfer of Select 10x10 and 14x14 TQFP_EP Products to Amkor Philippines

Publication Date: 18-May-2015

Effectivity Date: 16-Aug-2015 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Adding parts being transferred.
Including Qualification Results Summary for 10x10 TQFP_EP Using G700L/3230.
Revising the estimated qual completion date of attachment2(14x14 TQFP_EP Using G631HQ_3230 at AP_Automotive) from April 2015 to June 2015.

Description Of Change

ADI is transferring to qualified subcontractor Amkor Philippines for the assembly of 10x10 and 14x14 TQFP_EP products. ADI will be qualifying Amkor's standard bill of materials(BOM). The mold compound material for 14x14 body packages will change from Sumitomo G700L to Sumitomo G631HQ. The mold gate position will change as a result of the mold compound change. The package outline dimensions and wire sizes of each product will be maintained.

Reason For Change

ADI is transferring to Amkor Philippines due to the closure of Amkor Korea factory lines in October 2015 for 10x10 TQFP_EP and November 2015 for 14x14 TQFP_EP.

ADI's assembly subcontractors manufacture products using Analog Devices specified manufacturing flows, materials, process controls and monitors, ensuring the same level of quality and reliability.

Impact of the change (positive or negative) on fit, form, function & reliability

The transfer will have no impact on the form, fit, function and reliability of the devices.

Product Identification *(this section will describe how to identify the changed material)*

The parts that will be assembled after the transfer will be identified by assembly lot number and the country of origin.

Summary of Supporting Information

Qualification will be performed per AEC-Q100, Stress Test Qualification for Integrated Circuits. See attached Qualification Plans.

Supporting Documents

Attachment 1: Type: Detailed Parts List

Attachment 2: Type: Qualification Plan

ADI_PCN_14_0259_Rev_A_14x14_TQFP_EP_Using_G631HQ_3230_at_AP_Automotive.docx

Attachment 3: Type: Qualification Results Summary

ADI_PCN_14_0259_Rev_A_Automotive_Qualification_Results_Summary_of_10x10_TQFP_EP_Using_G700L_3230_at_AP.pdf

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas: PCN_Americas@analog.com

Europe: PCN_Europe@analog.com

Japan: PCN_Japan@analog.com

Rest of Asia: PCN_ROA@analog.com

Appendix A - Affected ADI Models

Existing Parts - Product Family / Model Number (7)

AD8284 / AD8284WCSVZ	ADAU1442 / ADAU1442YSVZ-3A	ADAU1442 / ADW80000YSVZ	ADAU1442 / ADW80000YSVZ-RL	ADAU1445 / ADW80001YSVZ
ADAU1445 / ADW80001YSVZ-RL	ADAU1445 / ADW80009BSVZ			

Added Parts On This Revision - Product Family / Model Number (3)

AD8284 / AD8284WCSVZ-RL	ADAU1442 / ADAU1442YSVZ-3A-RL	ADAU1445 / ADW80009BSVZ-RL		
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Appendix B - Revision History

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	10-Dec-2014	01-May-2015	Initial Release
Rev. A	18-May-2015	16-Aug-2015	Adding parts being transferred. Including Qualification Results Summary for 10x10 TQFP_EP Using G700L/3230. Revising the estimated qual completion date of attachment2(14x14 TQFP_EP Using G631HQ_3230 at AP_Automotive) from April 2015 to June 2015.

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DocId:3255 Parent DocId:None Layout Rev:7

FG Model	Pkg Type	Body Size	PkgLead Count	WIRE DIA. (BEFORE)	WIRE DIA. (AFTER)	EPOXY (BEFORE)	EPOXY (AFTER)	MOLD (BEFORE)	MOLD (AFTER)	MOLD GATE POSITION (BEFORE)	MOLD GATE POSITION (AFTER)
AD8284WCSVZ	TQFP_EP	10X10X1.0	64	1	1	3230	3230	G700L	G700L	Pkg Corner	Pkg Corner
AD8284WCSVZ-RL	TQFP_EP	10X10X1.0	64	1	1	3230	3230	G700L	G700L	Pkg Corner	Pkg Corner
ADAU1442YSVZ-3A	TQFP_EP	14X14X1.0	100	1	1	3230	3230	G700L	G631HQ	Pkg Corner	Package top side, opposite corner of Pin 1 mark
ADAU1442YSVZ-3A-RL	TQFP_EP	14X14X1.0	100	1	1	3230	3230	G700L	G631HQ	Pkg Corner	Package top side, opposite corner of Pin 1 mark
ADW80001YSVZ	TQFP_EP	14X14X1.0	100	1	1	3230	3230	G700L	G631HQ	Pkg Corner	Package top side, opposite corner of Pin 1 mark
ADW80001YSVZ-RL	TQFP_EP	14X14X1.0	100	1	1	3230	3230	G700L	G631HQ	Pkg Corner	Package top side, opposite corner of Pin 1 mark
ADW80009BSVZ	TQFP_EP	14X14X1.0	100	1	1	3230	3230	G700L	G631HQ	Pkg Corner	Package top side, opposite corner of Pin 1 mark
ADW80009BSVZ-RL	TQFP_EP	14X14X1.0	100	1	1	3230	3230	G700L	G631HQ	Pkg Corner	Package top side, opposite corner of Pin 1 mark
ADW80000YSVZ	TQFP_EP	14X14X1.0	100	1	1	3230	3230	G700L	G631HQ	Pkg Corner	Package top side, opposite corner of Pin 1 mark
ADW80000YSVZ-RL	TQFP_EP	14X14X1.0	100	1	1	3230	3230	G700L	G631HQ	Pkg Corner	Package top side, opposite corner of Pin 1 mark